

FEATURES

- | Low profile package
- | Ideal for automated placement
- | 3000 Watt peak pulse power capability with a 10/1000µs waveform
- | For surface mounted applicatons to optimize board space
- | Excellent clamping capability
- | Very fast response time
- | Low incremental surge resistance
- | Meet AEC-Q101 Requirements



DO-214AB(SMC)



Schematic Symbol

APPLICATIONS

- | Power supply protection
- | Automotive application
- | Industrial application
- | Power management

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation on 10/1000µs waveform (Note1, Note2).	P_{PPM}	3000	Watts
Steady State Power Dissipation at $T_L=50^{\circ}\text{C}$, Lead lengths.375" (9.5mm) (Note2)	P_D	6.5	Watts

Notes : 1.Non-repetitive current pulse, $T_A=25^{\circ}\text{C}$.
 2.Mounted on 5.0mm*5.0mm (0.03mm thick) Copper Pads to each terminal.

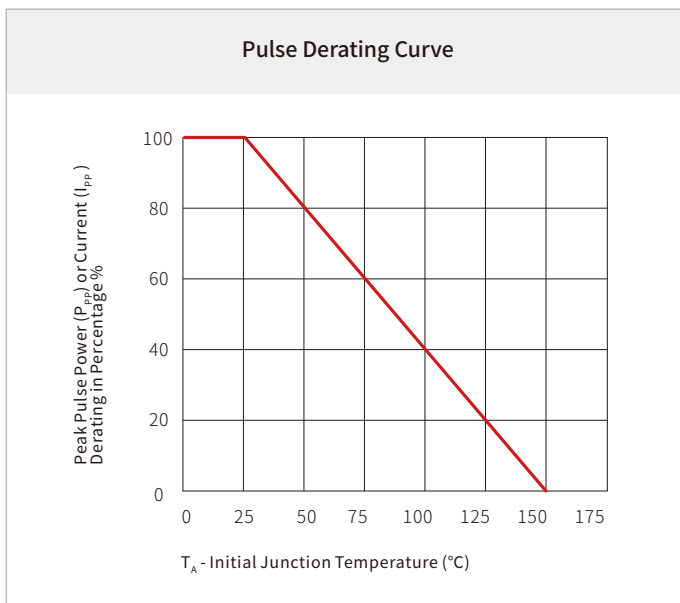
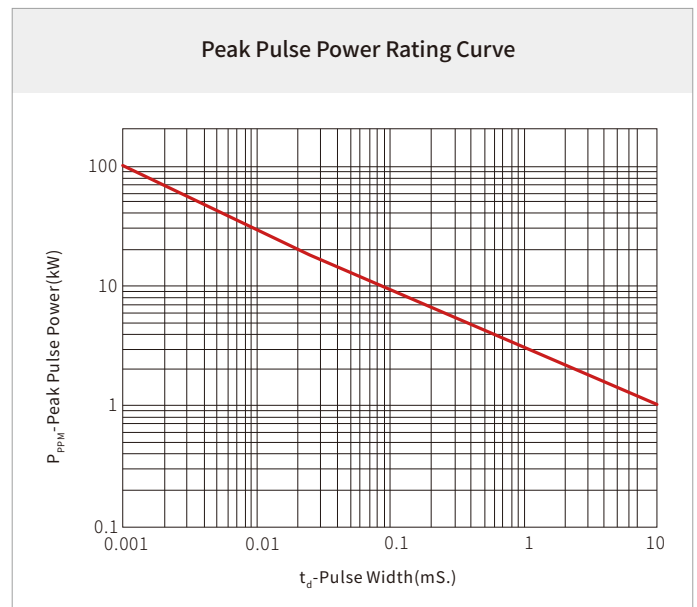
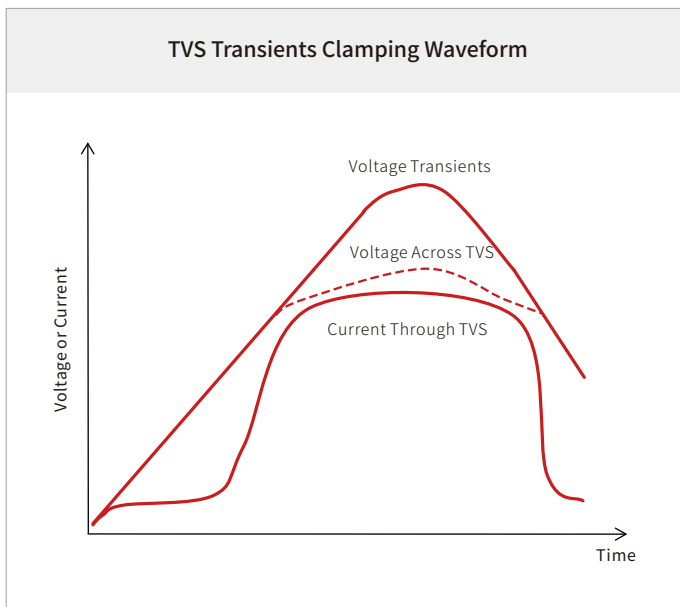
THERMAL CONSIDERATIONS

Parameter	Symbol	Value	Unit
Operating Junction Temperature	T_J	-55 to +150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^{\circ}\text{C}$
Junction to Ambient on printed circuit	$R_{\theta JA}$	75	$^{\circ}\text{C/W}$

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$)

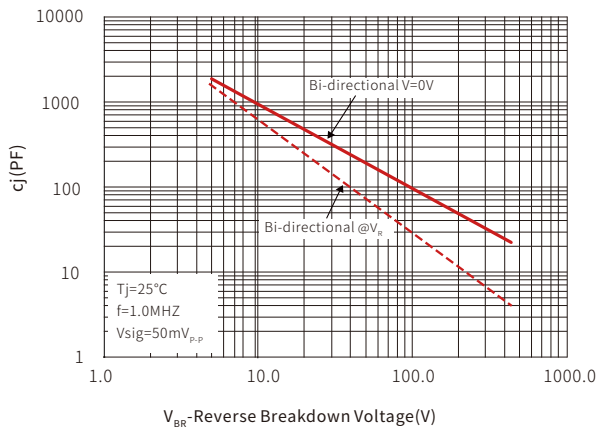
Part Number	Device Marking Code	Reverse Stand-off Voltage	Breakdown Voltage Min.@ I_T	Breakdown Voltage Max.@ I_T	Test Current	Maximum Clamping Voltage @ I_{PP}	Peak Pulse Current	Reverse Leakage @ V_{RWM}
		V_{RWM} (V)	V_{BR} (V)	V_{BR} (V)	I_T (mA)	V_C (V)	I_{PP} (A)	I_R (uA)
TPSVC300B13	DEGA	13.0	14.4	15.9	1.0	21.5	139.5	1.0

CHARACTERISTIC CURVES

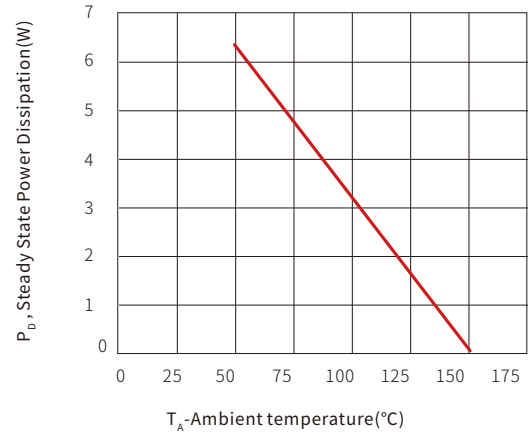




Typical Junction Capacitance

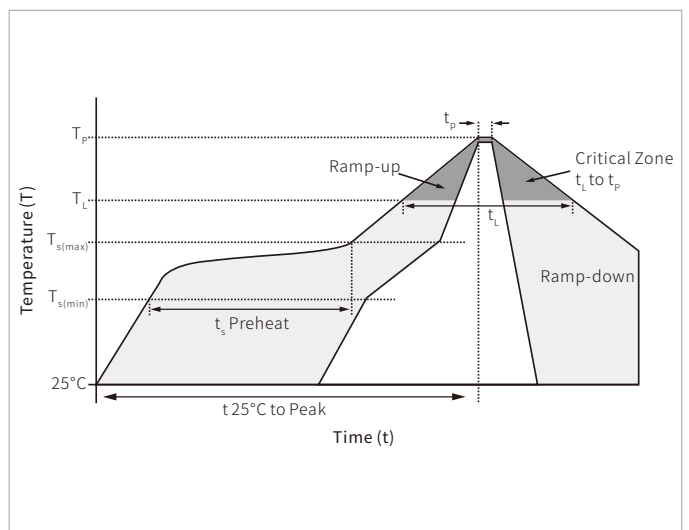


Steady State Power Dissipation Derating Curve

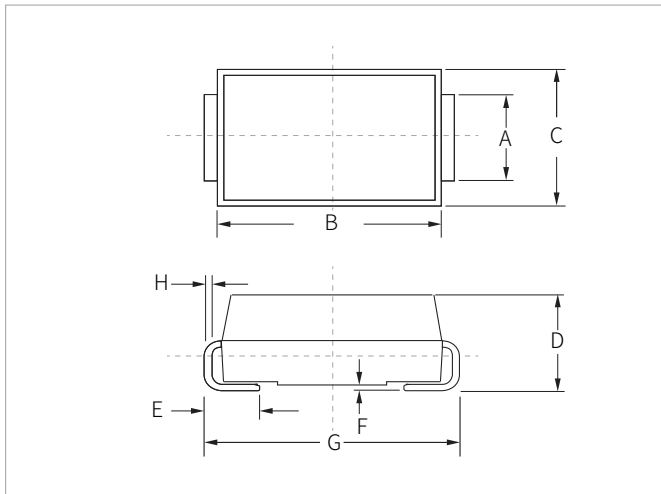


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max (T _{s(min)})	150°C
	Temperature Max (T _{s(max)})	200°C
	Time (min to max) (t _s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T _L) to peak)		3°C/second max
T _{s(max)} to T _L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T _L) (Liquidus)	217°C
	Time (min to max) (t _L)	60 – 150 seconds
Peak Temperature (T _p)		260°C
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T _p)		8 minutes max.
Do not exceed		260°C

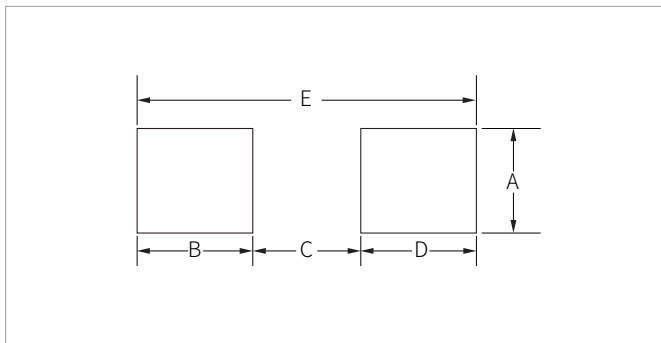


DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.20	0.110	0.126
B	6.60	7.20	0.260	0.283
C	5.70	6.10	0.224	0.240
D	2.15	2.75	0.085	0.108
E	1.00	1.60	0.039	0.063
F	0.02	0.20	0.000	0.008
G	7.60	8.00	0.299	0.315
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	-	0.129	-
B	2.40	-	0.094	-
C	-	4.20	-	0.165
D	2.40	-	0.094	-
E	8.20REF		0.323REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
TPSVC300B13	DO-214AB(SMC)	3000PCS	13"

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